SN5402, SN54LS02, SN54S02, SN7402, SN74LS02, SN74S02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

DECEMBER 1983-REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

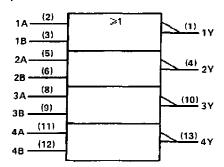
These devices contain four independent 2-input-NOR gates.

The SN5402, SN54LS02, and SN54S02 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN7402, SN74LS02, and SN74S02 are characterized for operation from 0°C to 70°C .

FUNCTION TABLE (each gate)

	INP	UTS	OUTPUT
ı	A	В	Y
	Н	Х	L
	Х	Н	L
Ì	Ł	L] н

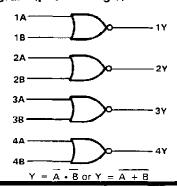
logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

logic diagram (positive logic)



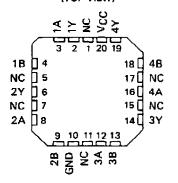
SN5402...J PACKAGE
SN54LS02, SN54S02...J OR W PACKAGE
SN7402...N PACKAGE
SN74LS02, SN74S02...D OR N PACKAGE
(TOP VIEW)

1Y	Цī	U14 VC0
1A	₫2	13∏ 4Y
18	□3	12 3 4 B
2Y	□4	11 4A
2A		10 3 Y
2B	□ 6	9 <u></u> 3 B
GND	d7	g <u> </u> 3A

SN5402 . . . W PACKAGE (TOP VIEW)

1A 🗀	ī	U	巾	4Y
18 [2	1:	3	4B
1Y 🗀	3	1;	冲	4A
V¢¢ □	4	• 1	巾	GND
2Y 🗀	5	1 (巾	3B
2A 🗀	6	9	ь	3A
2B 🗀	7	8	Þ	3Y

SN54LS02, SN54S02 . . . FK PACKAGE (TOP VIEW)

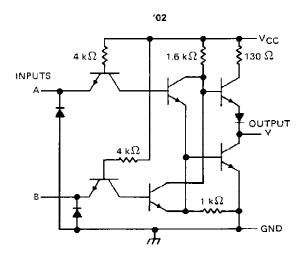


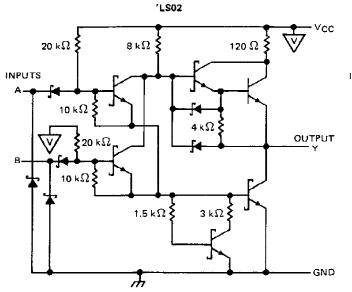
NC - No internal connection

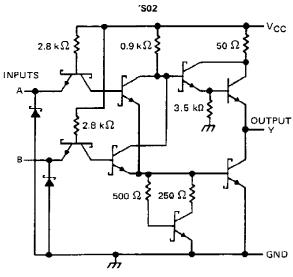
PRODUCTION DATA documents contain information current as of publication dats. Preducts conform to specifications per the terms of Tuxas Instruments standard warranty. Production processing does not necessarily include tasting of all parameters.



schematics (each gate)







Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
	5.5 V
'LS02	, , ,
Off-state output voltage	,
Operating free-air temperature range:	SN54'55°C to 125°C
	SN74'
Storage temperature range	, -65°C to 150°C

NOTE 1. Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN5402			SN7402			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vac 5	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧	
V _{IH} I	High-level input voltage	2			2			٧	
VIL I	Low-level input voltage			8.0			0.8	٧	
Іон І	High-level output current			- 0.4			- 0.4	mΑ	
loL l	Low-level output current			16			16	mA	
T _A (Operating free-air temperature	55		125	٥		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TECT COMPLETIONS *			\$N5402			SN7402			
PARAMETER		TEST CONDITIONS †			TYP#	MAX	MIN	TYP‡	MAX	UNIT
Vικ	V _{CC} = MIN,	l = - 12 mA				- 1.5			- 1.5	V
VOH	V _{CC} = MIN,	V _{IL} = 0.8 V.	I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		٧
V _{OL}	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
Ц	V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
11H	V _{CC} = MAX,	V1 = 2.4 V				40			40	μΑ
I _{IL}	V _{CC} = MAX,	V ₁ = 0.4 V				- 1.6			- 1.6	mΑ
¹ 0s§	V _{CC} = MAX			- 20		- 55	- 18		- 55	mΑ
^I ссн	V _{CC} = MAX,	V ₁ = 0 V	·	_	8	16		8	16	mΑ
CCL	V _{CC} = MAX,	See Note 2			14	27		14	27	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		TYP	MAX	UNIT
t _{PLH}					12	22	ns
^t PHL	A or B	Υ	$R_L = 400 \Omega$, $C_L = 15 pF$		8	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at VCC = 5 V, TA = 25°C.

[§] Not more than one output should be shorted at a time.

SN54LS02, SN74LS02 QUADRUPLE 2 INPUT POSITIVE NOR GATES

recommended operating conditions

	SN54LS02 SN74LS02	
	MIN NOM MAX MIN NOM MA	AX VNIT
V _{CC} Supply voltage	4.5 5 5.5 4.75 5 5.	.25 V
V _{IH} High-level input voltage	2 2	٧
VIL Low-level input voltage	0.7	0.8 V
OH High-level output current	- 0.4	0.4 mA
IOL Low-level output current	4	8 mA
TA Operating free-air temperature	- 55 125 0	70 °C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS T			SN54LS	502		SN74LE	02	l	
PARAMÉTER		TEST CONDITIONS (MIN	TYP‡	MAX	MIN	TYP\$	MAX	UNIT
٧ıĸ	VCC = MIN,	I ₁ = 18 mA				– 1.5			– 1.5	V
∨он	V _{CC} = MIN,	VIL = MAX,	¹ OH = - 0.4 mA	2.5	3.4		2.7	3.4		٧
V _{OL}	V _{CC} - MIN,	V _{1H} = 2 V,	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
	VCC = MIN,	V _{IH} = 2 V,	IOL = 8 mA					0.35	0.5] *
t _i	V _{CC} = MAX,	V _I = 7 V	· ·			0.1			0 .1	mΑ
Чн	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μА
HL	V _{CC} = MAX,	V) = 0.4 V				- 0.4			- 0.4	mΑ
los§	V _{CC} - MAX			- 20		- 100	- 20		- 100	mΔ
Іссн	V _{CC} = MAX,	V _I = 0 V			1.6	3.2		1.6	3.2	mА
ICCL	VCC = MAX,	See Note 2			2.8	5.4		2.8	5.4	mΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN TYP	MAX	UNIT	
₹PLH	A or R	V	D. = 2k0	C 15 pc	10	15	nş
ФНL	A or B	'	RL = 2 kΩ,	C _L = 15 pF	10	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second. NOTE 2: One input at 4.5 V, all others at GND.

recommended operating conditions

			SN54S02			SN74S02		
		MIN	MIN NOM MAX MIN NOM MAX	UNIT				
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	v
VIH	High-level input voltage	2		-	2			٧
۷ĮĻ	Low-level input voltage			8.0			0.8	V
lон	High-level output current			- 1			– 1	mΑ
loL	Low-level output current			20			20	mΑ
Тд	Operating free-air temperature	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS T			SN54S02			SN74S02			
PARAMETER			MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIK	V _{CC} - MIN,	I _I = -18 mA				-1.2			-1,2	٧
Voн	V _{CC} = MIN,	V _{1L} = 0.8 V,	I _{OH} = - 1 mA	2.5	3.4		2.7	3.4		٧
VOL	VCC = MIN,	V _{IH} = 2 V.	IOL = 20 mA			0.5			0.5	V
l _I	V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
ЧН	V _{CC} = MAX,	V ₁ = 2.7 V				50			50	μА
Iμ	V _{CC} = MAX,	V = 0.5 V				-2			-2	mA
l _{OS} §	V _{CC} = MAX			-40		-100	-40		-100	mA
Іссн	V _{CC} = MAX,	V _I = 0 V			17	29		17	29	mΑ
lccr	V _{CC} = MAX,	See Note 2	· · · · · · · · · · · · · · · · · · ·		26	45		26	45	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN TYP	MAX	UNIT
tPLH			$R_1 = 280 \Omega$, $C_1 = 15 \rho F$	3.5	5,5	ns
tPHL	A D	v	R _L = 280 Ω, C _L = 15 pF	3.5	5,5	ns
tPLH	A or B	Y	D = 200 C = 50 c 5	5		ns
tPHL			$R_L = 280 \Omega$, $C_L = 50 pF$	5		ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.





11-Jul-2015

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00401BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00401BCA	Samples
JM38510/00401BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00401BDA	Samples
JM38510/00401BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00401BDA	Samples
JM38510/07301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07301BCA	Samples
JM38510/07301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07301BCA	Samples
JM38510/07301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07301BDA	Samples
JM38510/07301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07301BDA	Samples
JM38510/30301B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30301B2A	Samples
JM38510/30301B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30301B2A	Samples
JM38510/30301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301BCA	Samples
JM38510/30301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301BCA	Samples
JM38510/30301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301BDA	Samples
JM38510/30301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301BDA	Samples
JM38510/30301SCA	LIFEBUY	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301SCA	
JM38510/30301SCA	LIFEBUY	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301SCA	
JM38510/30301SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301SDA	Samples
JM38510/30301SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301SDA	Samples





Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
M38510/00401BCA	ACTIVE	CDIP	J	14	1	TBD	(6) A42	N / A for Pkg Type	-55 to 125	JM38510/ 00401BCA	Sample
M38510/00401BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00401BCA	Samples
M38510/00401BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00401BDA	Sample
M38510/00401BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 00401BDA	Sample
M38510/07301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07301BCA	Sample
M38510/07301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07301BCA	Sample
M38510/07301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07301BDA	Sample
M38510/07301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07301BDA	Sample
M38510/30301B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30301B2A	Sample
M38510/30301B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30301B2A	Sample
M38510/30301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301BCA	Sample
M38510/30301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301BCA	Sample
M38510/30301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301BDA	Sample
M38510/30301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301BDA	Sample
M38510/30301SCA	LIFEBUY	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301SCA	
M38510/30301SCA	LIFEBUY	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301SCA	
M38510/30301SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301SDA	Sample
M38510/30301SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30301SDA	Sample



Orderable Device	Status	Package Type	_	Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN5402J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5402J	Sample
SN5402J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5402J	Sample
SN54LS02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS02J	Sample
SN54LS02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS02J	Sample
SN54S02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S02J	Sample
SN54S02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S02J	Sample
SN7402N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7402N	Sampl
SN7402N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7402N	Sampl
SN7402N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7402N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7402NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7402N	Samp
SN7402NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7402N	Sampl
SN74LS02D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Samp
SN74LS02D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Sampl
SN74LS02DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Samp
SN74LS02DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Samp
SN74LS02DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Samp
SN74LS02DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Samp
SN74LS02DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Samp
SN74LS02DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Samp



Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS02DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Samples
SN74LS02DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS02	Samples
SN74LS02J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS02J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS02N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS02N	Samples
SN74LS02N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS02N	Samples
SN74LS02N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS02N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS02NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS02N	Samples
SN74LS02NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS02N	Samples
SN74LS02NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS02	Samples
SN74LS02NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS02	Samples
SN74LS02NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS02	Samples
SN74LS02NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS02	Samples
SN74S02D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S02	Samples
SN74S02D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S02	Samples
SN74S02DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S02DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74S02N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S02N	Samples
SN74S02N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S02N	Samples
SN74S02N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		





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Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74S02N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SNJ5402J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5402J	Sample
SNJ5402J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5402J	Sample
SNJ5402W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5402W	Sample
SNJ5402W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ5402W	Sample
SNJ54LS02FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 02FK	Sample
SNJ54LS02FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 02FK	Sampl
SNJ54LS02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS02J	Sampl
SNJ54LS02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS02J	Sampl
SNJ54LS02W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS02W	Sampl
SNJ54LS02W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS02W	Sampl
SNJ54S02FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 02FK	Sampl
SNJ54S02FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 02FK	Sampl
SNJ54S02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S02J	Sampl
SNJ54S02J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S02J	Samp
SNJ54S02W	LIFEBUY	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S02W	
SNJ54S02W	LIFEBUY	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S02W	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

PACKAGE OPTION ADDENDUM



11-Jul-2015

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN5402, SN54LS02, SN54LS02-SP, SN54S02, SN7402, SN74LS02, SN74S02:

Catalog: SN7402, SN74LS02, SN54LS02, SN74S02

Military: SN5402, SN54LS02, SN54S02

Space: SN54LS02-SP

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product



PACKAGE OPTION ADDENDUM

- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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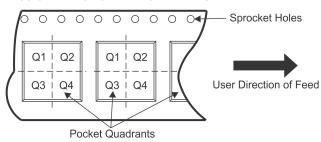
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS02DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

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*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	SN74LS02DR	SOIC	D	14	2500	367.0	367.0	38.0	

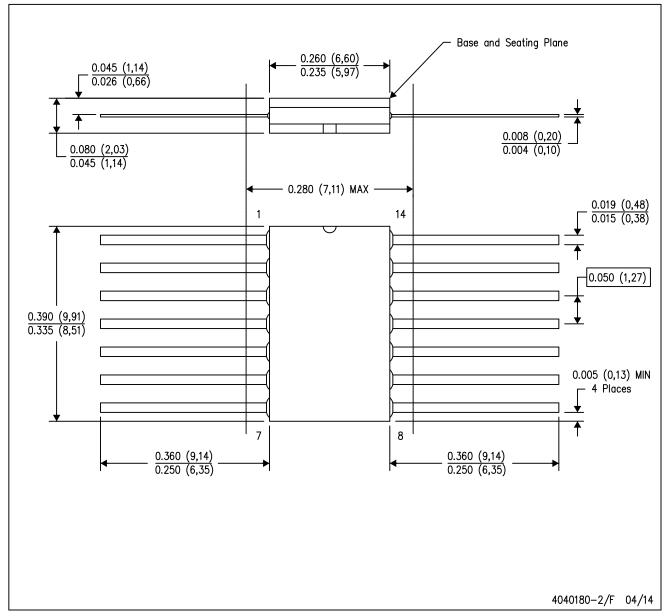
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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